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FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 34091/US	APPLICATION NO. 10/783,662
INFORMATION DISCLOSURE STATEMENT *(Use several sheets if necessary)*		APPLICANT(S) Peter C. Salmon	
		FILING DATE February 20, 2004	GROUP ART UNIT 2823

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	4,455,654	06/19/84	Bhaskar et al.	714	28	
	AB	4,748,495	05/31/88	Kucharek	257	713	
	AC	4,862,322	08/29/89	Bickford et al.	361	718	
	AD	4,912,844	04/03/90	Parker	29	848	
	AE	5,001,548	03/19/91	Iversen	257	714	
	AF	5,159,529	10/27/92	Lovgren	361	699	
	AG	5,162,974	11/10/92	Currie	361	702	
	AH	5,214,250	05/25/93	Cayson et al.	438	73	
	AI	5,239,200	08/24/93	Messina et al.	257	714	
	AJ	5,267,867	12/07/93	Agahdel et al.	439	73	
	AK	5,290,970	03/01/94	Currie	174	250	
	AL	5,305,184	04/19/94	Andresen et al.	361	699	
	AM	5,334,279	08/02/94	Gregoire	216	20	
	AN	5,367,593	11/22/94	Lebby et al.	385	53	
	AO	5,390,412	02/21/95	Gregoire	29	848	
	AP	5,451,722	09/19/95	Gregoire	174	261	
	AQ	5,579,574	12/3/96	Colleran et al.	29	840	
	AR	5,627,406	05/06/97	Pace	257	700	
	AS	5,774,475	06/30/98	Qureshi	714	726	
	AT	5,800,060	09/01/98	Speckbrock et al.	374	104	
	AU	5,900,738	05/04/99	Khandros et al.	324	761	
	AV	5,972,152	10/26/99	Lake et al.	156	247	
	AW	5,998,738	12/07/99	Li et al.	174	250	
	AX	6,005,198	12/21/99	Gregoire	174	262	

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	AY	6,103,554	08/14/00	Son et al.	438	126	
	AZ	6,121,676	09/19/00	Solberg	257	686	
	BA	6,138,348	10/31/00	Kulesza et al.	29	840	
	BB	6,174,804	01/16/01	Hsu	438	238	
	BC	6,208,511	03/27/01	Bortolini et al.	361	698	
	BD	6,225,688	05/01/01	Kim et al.	257	686	
	BE	6,246,010	06/12/01	Zenner et al.	174	260	
	BF	6,304,447	10/16/01	Bortolini et al.	361	699	
	BG	6,310,484	10/30/01	Akram et al.	324	764	
	BH	6,372,549	04/16/02	Urushima	438	118	
	BI	6,441,476	08/27/02	Emoto	257	686	
	BJ	6,460,247	10/08/02	Gregoire	29	848	
	BK	6,515,870	02/04/03	Skinner et al.	361	800	
	BL	6,528,891	03/04/03	Lin et al.	257	778	
	BM	6,587,345	07/01/03	Chu et al.	361	719	
	BN	6,631,344	10/07/03	Kapur et al.	703	22	
	BO	6,683,377	01/27/04	Shim et al.	257	723	
	BP	6,722,893	04/20/04	Li et al.	439	66	
	BQ	6,763,880	07/20/04	Shih	165	80.4	
	BR	6,845,477	01/18/05	Hidaka	714	729	
	BS	6,881,609	04/19/05	Salmon	438	107	
	BT	6,927,471	08/09/05	Salmon	257	499	
	BU	6,938,678	09/06/05	Bortolini et al.	165	80.4	
	BV	6,942,493	09/13/05	Matsunaga et al.	439	66	

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	BW	6,955,063	10/18/05	Adiga et al.	62	259.2	
	BX	6,956,284	10/18/05	Cady et al.	257	685	
	BY	6,973,717	12/13/05	Hacke et al.	29	840	
	BZ	6,990,176	01/24/06	Sherman et al.	378	98.8	
	CA	7,009,412	03/07/06	Chong et al.	324	754	
	CB	7,040,383	05/09/06	Oyamada	165	104.33	
	CC	7,078,926	07/18/06	Khandros et al.	324	765	
	CD	7,163,830	01/16/07	Salmon et al.	438	18	
	CE	7,254,024	08/07/07	Salmon	361	699	
	CF	US 2002/0030975	03/14/02	Moon	361	749	
	CG	US 2003/0106004	06/05/03	Richetti et al.	714	733	
	CH	US 2003/0168725	09/11/03	Warner et al.	257	686	
	CI	US 2004/0148121	07/29/04	deObaldi et al.	702	117	
	CJ	US 2004/0176924	09/9/04	Salmon	702	125	
	CK	US 2005/0184376	08/25/05	Salmon	257	686	
	CL	US 2005/0255722	11/07/05	Salmon	439	67	
	CM	US 2006/0077638	04/13/06	Salmon	361	704	
	CN	US 2006/0131728	06/22/06	Salmon	257	698	
	CO	US 2006/0209512	09/21/06	Taniguchi et al.	361	699	
	CP	US 2007/0007983	01/11/07	Salmon	324	754	
	CQ	US 2007/0023889	02/01/07	Salmon	257	690	
	CR	US 2007/0023904	02/01/07	Salmon	385	049	
	CS	US 2007/0023923	02/01/07	Salmon	257	296	
	CT	US 2007/0025079	02/01/07	Salmon	361	699	

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FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
	DG	JP07169873A	7/4/95	Japan (English abstract)	H01L023	23		X
	DH							

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	DI	Chow, Eugene M. et al., "Process Compatible Polysilicon-Based Electrical Through-Wafer Interconnects in Silicon Substrates", Journal of Microelectromechanical Systems, Vol. 11, No. 6, December 2002, pp. 631-640
	DJ	Davis & Arledge, "Thin Film Metallization of Three Dimensional Substrates", Electronic Components Technology Conference, Proceedings 44th, May 1-4, 1994, pp. 359-361
	DK	Gutmann, R.J. et al., "Wafer-Level Three-Dimensional Ics: A Better Solution Than SoCs and SiPs?", 6 pages
	DL	Holden, Happy, "A Design Technology Innovation – The Power Mesh Architecture for PCBs", The Board Authority, December 2000, pp. 2-6
	DM	Kreider, Kenneth G. et al., "High Temperature Materials For Thin-Film Thermocouples On Silicon Wafers", Chemical Science and Technology Laboratory, NIST, Gaithersburg, Maryland, USA
	DN	Sensu, Yoshihisa et al., "Study on Improved Resolution of Thick Film Resist (Verification by Simulation)", SPIE, 2001

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